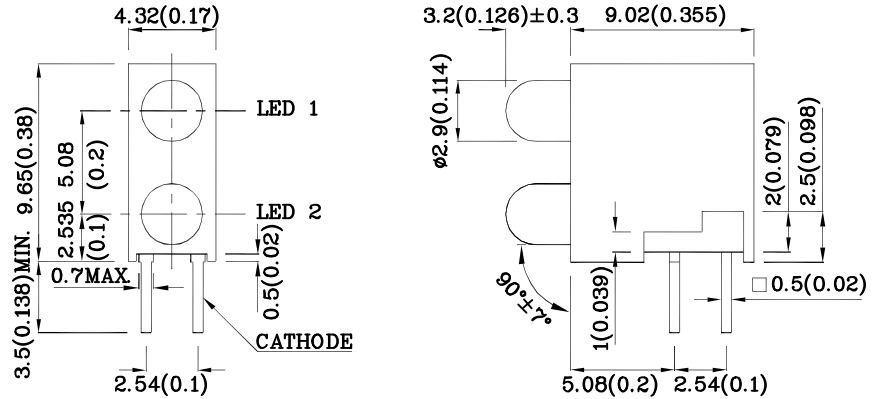


**Features**

- Housing material: Type 66 Nylon
- Black casing provides superior contrast
- Housing UL rating: 94V-0
- Reliable & robust
- Custom color combinations available
- RoHS Compliant



**Package Schematics**



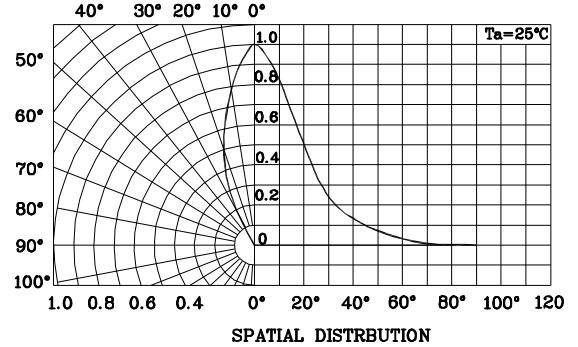
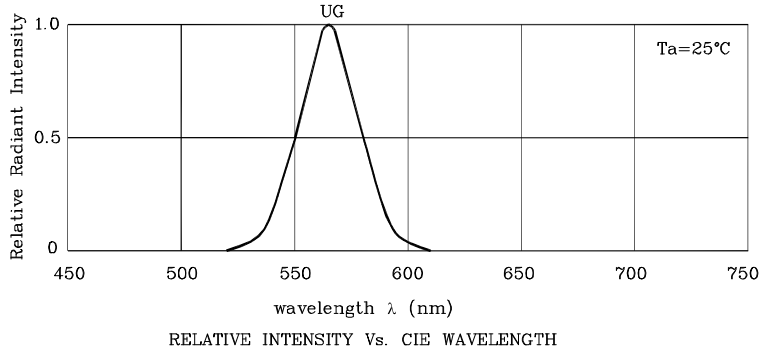
- Notes:  
 1. All dimensions are in millimeters (inches).  
 2. Tolerance is ±0.25(0.01") unless otherwise noted.  
 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)		UG (GaP)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	140	mA
Power Dissipation	P <sub>D</sub>	62.5	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

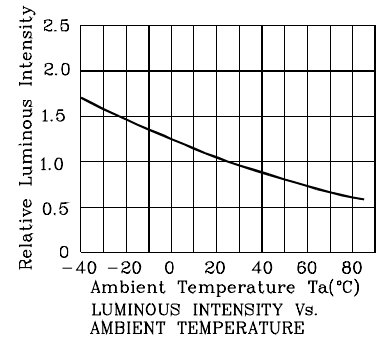
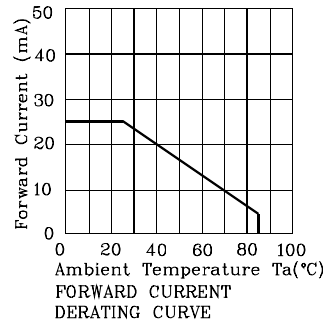
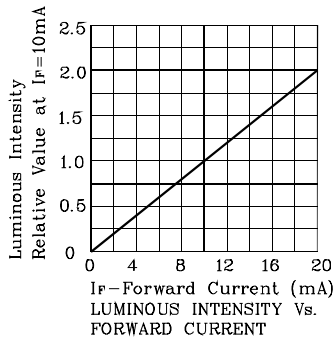
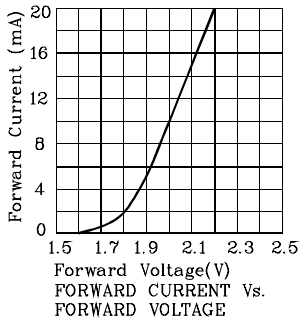
Operating Characteristics (T <sub>A</sub> =25°C)		UG (GaP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	2	V
Forward Voltage (Max.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	2.5	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	I <sub>R</sub>	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I <sub>F</sub> =10mA)	λ <sub>P</sub>	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I <sub>F</sub> =10mA)	λ <sub>D</sub>	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =10mA)	Δλ	30	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I <sub>F</sub> =10mA) mcd		Wavelength CIE127-2007* nm λ <sub>P</sub>	Viewing Angle 2θ 1/2
				min.	typ.		
XYN2LUG11D	Green	GaP	Green Diffused	12*	30*	565*	40°

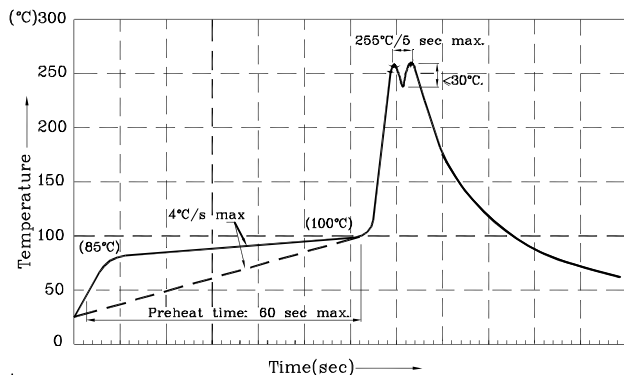
\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



❖ UG



Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



- Notes:
1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 280°C
  2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
  3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
  4. Fixtures should not incur stress on the component when mounting and during soldering process.
  5. SAC 305 solder alloy is recommended.
  6. No more than one wave soldering pass.

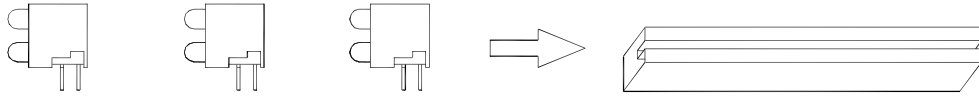
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

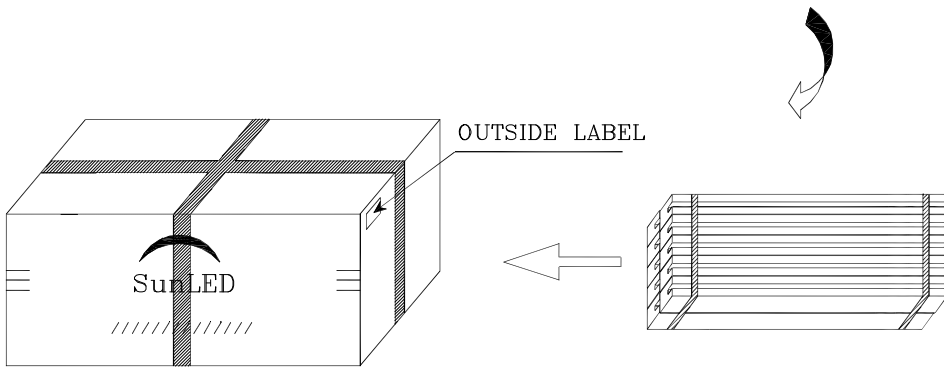
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS





115PCS / IC TUBE



16.1K / BOX

1150PCS / 10PCS IC TUBE

	<table border="1"> <tr> <td>Q.C.</td> </tr> <tr> <td style="text-align: center;">Q C</td> </tr> <tr> <td style="text-align: center;">XX XX XX</td> </tr> <tr> <td style="text-align: center;">PASSED</td> </tr> </table>	Q.C.	Q C	XX XX XX	PASSED
Q.C.					
Q C					
XX XX XX					
PASSED					
P/N0 : XYN2Lxx11x	FQC				
QTY : 1150 pcs	CODE: XXX				
S/N : XX					
LOT NO:					
 xxxxxxxxxxxxxxxxxxxxxxxx	RoHS Compliant				